Silicon Carbide Schottky Diode

650 V, 10 A

FFSD1065B

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 49 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

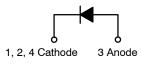
Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits



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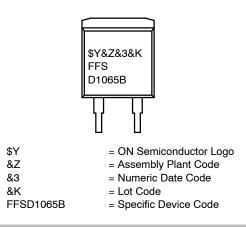


Schottky Diode



DPAK3 (TO-252, 3 LEAD) CASE 369AS

MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

FFSD1065B

Symbol	Parameter	Value	Unit	
V _{RRM}	Peak Repetitive Reverse Voltage		650	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		49	mJ
١ _F	Continuous Rectified Forward Current @ T _C < 150°C		10	A
	Continuous Rectified Forward Current @ T _C < 135°C		13.5	
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	650	А
		T _C = 150°C, 10 μs	570	А
I _{F,SM}	Non-Repetitive Forward Surge Current $T_{C} = 25^{\circ}C$	Half-Sine Pulse, t _p = 8.3 ms	45	A
Ptot	Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	98	W
		T _C = 150°C	16	W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C
	TO-247 Mounting Torque, M3 Screw	60	Ncm	

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. E_{AS} of 49 mJ is based on starting T_J = 25°C, L = 0.5 mH, I_{AS} = 14 A, V = 50 V.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max	1.53	°C/W

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	I _F = 10 A, T _C = 25°C	-	1.38	1.7	V
		I _F = 10 A, T _C = 125°C	-	1.6	2.0	
		I _F = 10 A, T _C = 175°C	-	1.72	2.4	
I _R	Reverse Current	$V_{R} = 650 \text{ V}, \text{ T}_{C} = 25^{\circ}\text{C}$	-	0.5	40	μΑ
		$V_{R} = 650 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	1	80	
		$V_{R} = 650 \text{ V}, \text{ T}_{C} = 175^{\circ}\text{C}$	-	2	160	
Q _C	Total Capacitive Charge	V = 400 V	-	25	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	424	-	pF
		V _R = 300 V, f = 100 kHz	-	39	-	
		V _R = 600 V, f = 100 kHz	-	35	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping*	
FFSD1065B	FFSD1065B	DPAK3 (Pb-Free / Halogen Free)	2500 / Tape & Reel	

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

FFSD1065B

TYPICAL CHARACTERISTICS

(T_J = 25°C unless otherwise noted)

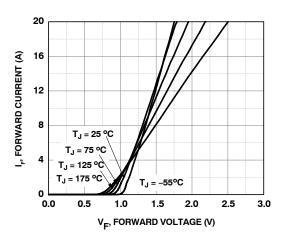
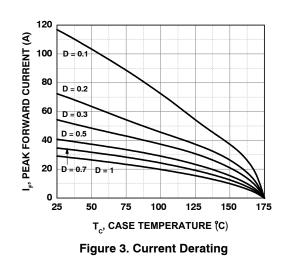


Figure 1. Forward Characteristics



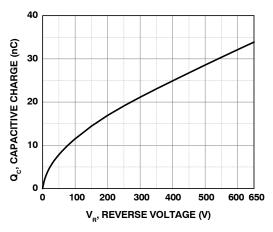


Figure 5. Capacitive Charge vs. Reverse Voltage

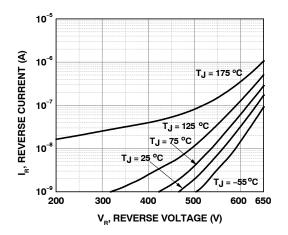
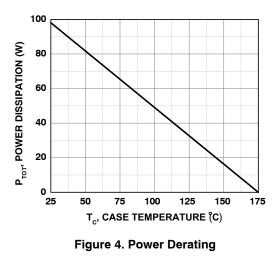


Figure 2. Reverse Characteristics



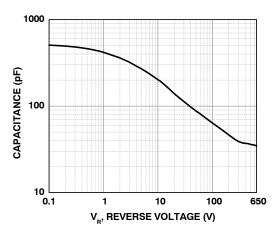


Figure 6. Capacitance vs. Reverse Voltage

FFSD1065B

TYPICAL CHARACTERISTICS (continued)

(T_J = 25°C unless otherwise noted)

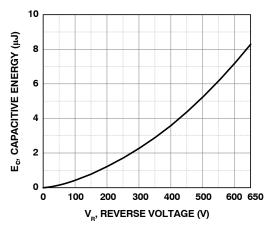


Figure 7. Capacitance Stored Energy

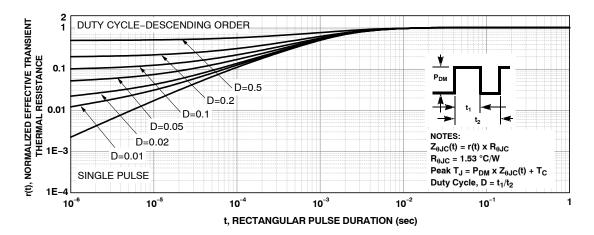
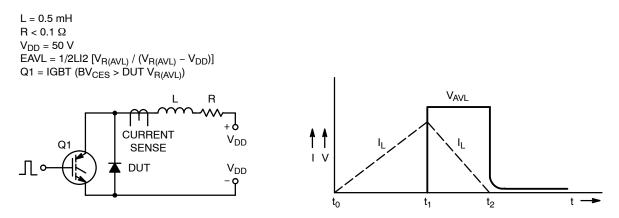


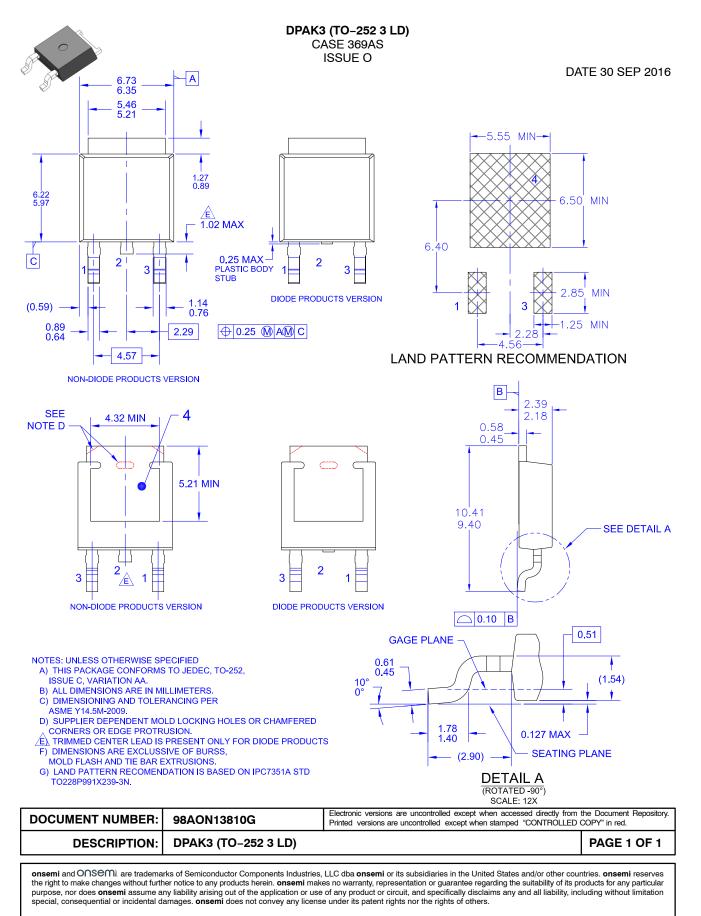
Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS





MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



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